



P9000-30 FRAME PROCESSING SYSTEM

Effective Way of Coating Wafers Mounted on Frames

Benefits

- Coats can be photoresist or polymers
- Capabilities to clean wafers on tape and to remove polymers and photoresist on frames after sawing or laser scribing
- Quick change chuck from different wafer/frame sizes
- Ability to coat very thin wafers mounted on frame and tape in preparation for laser scribing and/or sawing
- Cassette to cassette substrate transfer by central robot

Features

- Process 50 mm – 300 mm wafers mounted on frames
- Cassette mapping
- PC Windows-based operating system with smartPro GUI
- CE Mark

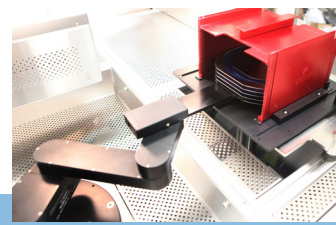
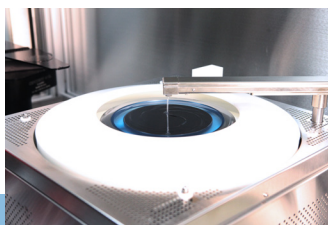
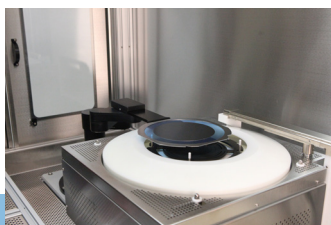
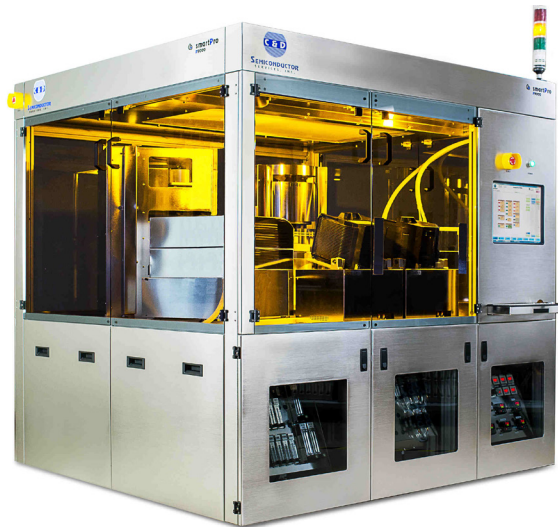
System Options

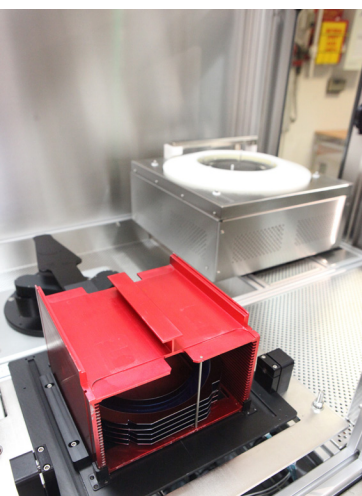
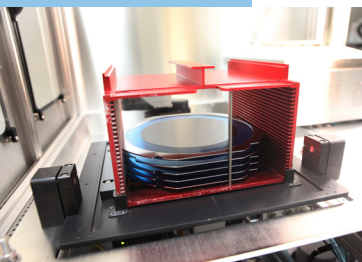
- SECS/GEM compliance
- Contact C&D for more options
- Barcode and recipe download
- Heated chemical
- Automatic chuck clean



Description

C&D's P9000-30 Frame Processing System is designed to be an effective way of coating wafers prior to saw or cleaning wafers post saw. With its high performance spindle motor and high accuracy stepper motor driving the dispense arm, the P9000-30 is proven reliable and repeatable. After final rinse, the system can be configured with a nitrogen blow off capability. The P9000-30 system can coat resists or polymers on thin wafers to assist with standard sawing or laser sawing. It can also be used to remove resist or protect coat polymers after saw.





Automatic or manual system

The P9000-30 Frame Processing system can be configured either as a manual system or an auto loading system with a central atmospheric robot. Either the automatic system or the manual system is configurable for many common frame sizes. The automated system can be configured for most common cassettes.

Both manual and automatic models offer a system designed with a user friendly and flexible software package.



Handle thin wafers

The system can handle an assortment of saw frame sizes and their complementary cassettes.

The P9000-30 Frame Processing System is proven to handle thin wafers on large frame tapes – with a solid history of handling 50 um thick sawn wafers.

C&D's P9000-30 holds a proven track record of gently cleaning wafers post saw or laser scribing, including its capability of handling solvent or caustic cleans.

Various wafers and frame sizes

C&D's unique counter balance chuck allows for safe handling of various types of frames, wafer sizes, and overall weight of the frame and substrate.

The chuck can be fabricated out of several types of materials to best suit the customer's process. The chuck design supports sawn substrates and prevents small die from being pulled down by vacuum.

P9000-30 Technical data

Available modules	Frame processing module and indexer
Wafer size	50 mm - 300 mm wafers mounted on frames
Transfer Method	Central atmospheric robot or manual transfer
User Interface	Windows-based operating system with smartPro GUI